**PRODUCT CHANGE NOTICE**

<table>
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<tr>
<th>PART NUMBER(S):</th>
<th>PCN No.: 06-0130-23</th>
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<tbody>
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<td>Please see attachment.</td>
<td>DATE: January 30, 2006</td>
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**PART DESCRIPTION:**

Power Management and Interface Products – Change in Wafer Fabrication Site

**LEVEL OF CHANGE:**

- [X] Level I, Customer Approval.
- [ ] Level II, Customer Information.

**PRODUCT ATTRIBUTE AFFECTED:**

- [ ] Material Change
- [ ] Design Change
- [X] Process Change
- [ ] Data Sheet Change
- [ ] Package Change
- [ ] Packing / Shipping
- [X] Other, Explain: Wafer Fabrication Site Transfer

**DESCRIPTION OF CHANGE:**

Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry Silan. See attached Product List no. 23.

**REASON FOR CHANGE:**

Power Management and Interface products as listed are being transferred to external wafer foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.

**FABRICATION PROCESS QUALIFICATION COMPLETED (DATE):** August 7, 2006

**PRODUCT CHARACTERIZATION COMPLETED AND SAMPLES* AVAILABLE (DATE):** June 19, 2006

* Samples representative of product from the Product Family being transferred.
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**EARLIEST DATE OF PRODUCTION SHIPMENTS:** November 16, 2006

**EFFECTIVITY CHANGE DATE OR DATE CODE:** Work week associated with earliest production shipment.

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<th>STANDARD DISTRIBUTION</th>
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**PERSON TO CONTACT WITH QUESTIONS:**

Fred Claussen

VP Quality Assurance and Reliability
Sipex Corporation
Phone Number: 408-935-7644
FAX NUMBER: 408-935-7678
PRODUCT CHANGE NOTICE

PCN No.: 06-0130-23
List 23

SP2209EEY
SP2209EEY-L